Burr-Brown Products
from Texas Instruments

VSP2262

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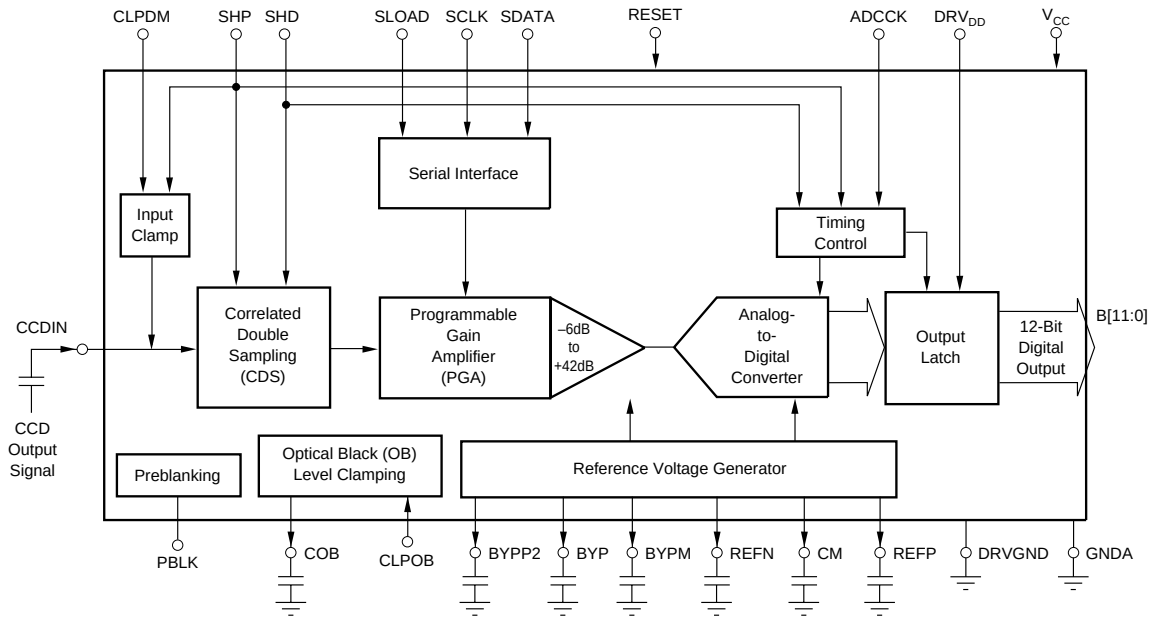
CCD SIGNAL PROCESSOR for DIGITAL CAMERAS

FEATURES

- **CCD SIGNAL PROCESSING:**
  Correlated Double Sampling (CDS)
  Programmable Black Level Clamping
- **PROGRAMMABLE GAIN AMPLIFIER (PGA):**
  –6dB to +42dB Gain Ranging
- **12-BIT DIGITAL DATA OUTPUT:**
  Up to 20MHz Conversion Rate
  No Missing Codes
- **79dB SIGNAL-TO-NOISE RATIO**
- **PORTABLE OPERATION:**
  Low Voltage: 2.7V to 3.6V
  Low Power: 83mW (typ) at 3.0V
  Stand-By Mode: 6mW

DESCRIPTION

The VSP2262 is a complete mixed-signal processing IC for digital cameras, providing signal conditioning and Analog-to-Digital (A/D) conversion for the output of a CCD array. The primary CCD channel provides Correlated Double Sampling (CDS) to extract video information from the pixels, –6dB to +42dB gain range with digital control for varying illumination conditions, and black level clamping for an accurate black level reference. Input signal clamping and offset correction of the input CDS are also performed. The stable gain control is linear in dB. Additionally, the black level is quickly recovered after gain change. The VSP2262Y is available in an LQFP-48 package and operates from a single +3V/+3.3V supply.



TEXAS INSTRUMENTS

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SPECIFICATIONS

At T_A = +25°C, V_{CC} = +3.0V, DRV_{DD} = +3.0V, Conversion Rate (f_{ADCCK}) = 20MHz, unless otherwise noted.

PARAMETER	CONDITIONS	VSP2262Y MIN	VSP2262Y TYP	VSP2262Y MAX	UNITS
RESOLUTION			12		Bits
CONVERSION RATE		20			MHz
DIGITAL INPUT					
Logic Family			TTL		
Input Voltage	LOW to HIGH Threshold Voltage (VT+)		1.7		V
	HIGH to LOW Threshold Voltage (VT–)		1.0		V
Input Current	Logic HIGH (I_{IH}) V_{IN} = +3V			±20	µA
	Logic LOW (I_{IL}) V_{IN} = 0V			±20	µA
DIGITAL OUTPUT					
Logic Family			CMOS		
Logic Coding			Straight Binary		
Output Voltage	Logic HIGH (V_{OH}) I_{OH} = –2mA	2.4			V
	Logic LOW (V_{OL}) I_{OL} = 2mA			0.4	V
ADCCK Clock Duty Cycle			50		%
Input Capacitance			5		pF
Maximum Input Voltage		–0.3		5.3	V
ANALOG INPUT (CCDIN)					
Input Signal Level for Full-Scale Out	PGA Gain = 0dB	900			mV
Input Capitance			15		pF
Input Limit		–0.3		3.3	V
TRANSFER CHARACTERISTICS					
Differential Non-Linearity (DNL)	PGA Gain = 0dB		±0.5		LSB
Integral Non-Linearity (INL)	PGA Gain = 0dB		±1		LSB
No Missing Codes			Guaranteed		
Step Response Settling Time	Full-Scale Step Input		1		Pixel
Overload Recovery Time	Step Input from 1.8V to 0V		2		Pixels
Data Latency			9 (Fixed)		Clock Cycles
Signal-to-Noise Ratio[1]	Grounded Input Cap, PGA Gain = 0dB		79		dB
	Grounded Input Cap, Gain = +24dB		55		dB
CCD Offset Correction Range		–180		200	mV
CDS					
Reference Sample Settling Time	Within 1LSB, Driver Impedance = 50Ω			11	ns
Data Sample Settling Time	Within 1LSB, Driver Impedance = 50Ω			11	ns
INPUT CLAMP					
Clamp-On Resistance			400		Ω
Clamp Level			1.5		V
PROGRAMMABLE GAIN AMP (PGA)					
Gain-Control Resolution			10		Bits
Maximum Gain	Gain Code = 1111111111		42		dB
High Gain	Gain Code = 1101001000		34		dB
Medium Gain	Gain Code = 1000100000		20		dB
Low Gain	Gain Code = 0010000000		0		dB
Minimum Gain	Gain Code = 0000000000		–6		dB
Gain Control Error			±0.5		dB
OPTICAL BLACK CLAMP LOOP					
Control DAC Resolution			10		Bits
Optical Black Clamp Level	Programmable Range of Clamp Level	2		60	LSB
	OBCLP Level at CODE = 1000		130		LSB
Min Output Current for Control DAC	COB Pin		±0.15		µA
Max Output Current for Control DAC	COB Pin		±153		µA
Loop Time Constant	C_{COB} = 0.1µF				µs
Slew Rate	C_{COB} = 0.1µF, Output Current from Control DAC is Saturated		1530		V/s
REFERENCE					
Positive Reference Voltage			1.75		V
Negative Reference Voltage			1.25		V
POWER SUPPLY					
Supply Voltage	V_{CC}, DRV_{DD}	2.7	3.0	3.6	V
Power Dissipation	Normal Operation Mode: No Load, DAC0 and DAC1 are Suspended		86		mW
	Stand-By Mode: f_{ADCCK} = Not Apply		6		mW
TEMPERATURE RANGE					
Operating Temperature		–25		+85	°C
Thermal Resistance θ_{JA}	LQFP-48		100		°C/W

NOTE: (1) SNR = 20 log(full-scale voltage/rms noise).

ABSOLUTE MAXIMUM RATINGS[1]

Supply Voltage: V_{CC}, DRV_{DD}	+4.0V
Supply-Voltage Differences: Among V_{CC}	±0.1V
Ground-Voltage Differences: Among GNDA	±0.1V
Digital Input Voltage	–0.3 to +5.3V
Analog Input Voltage	–0.3 to V_{CC} + 0.3V
Input Current (Any Pins Except Supplies)	±10mA
Ambient Temperature Under Bias	–40 to +125°C
Storage Temperature	–55 to +125°C
Junction Temperature	+150°C
Lead Temperature (Soldering, 5s)	+260°C
Package Temperature (IR Reflow, Peak, 10s)	+235°C

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

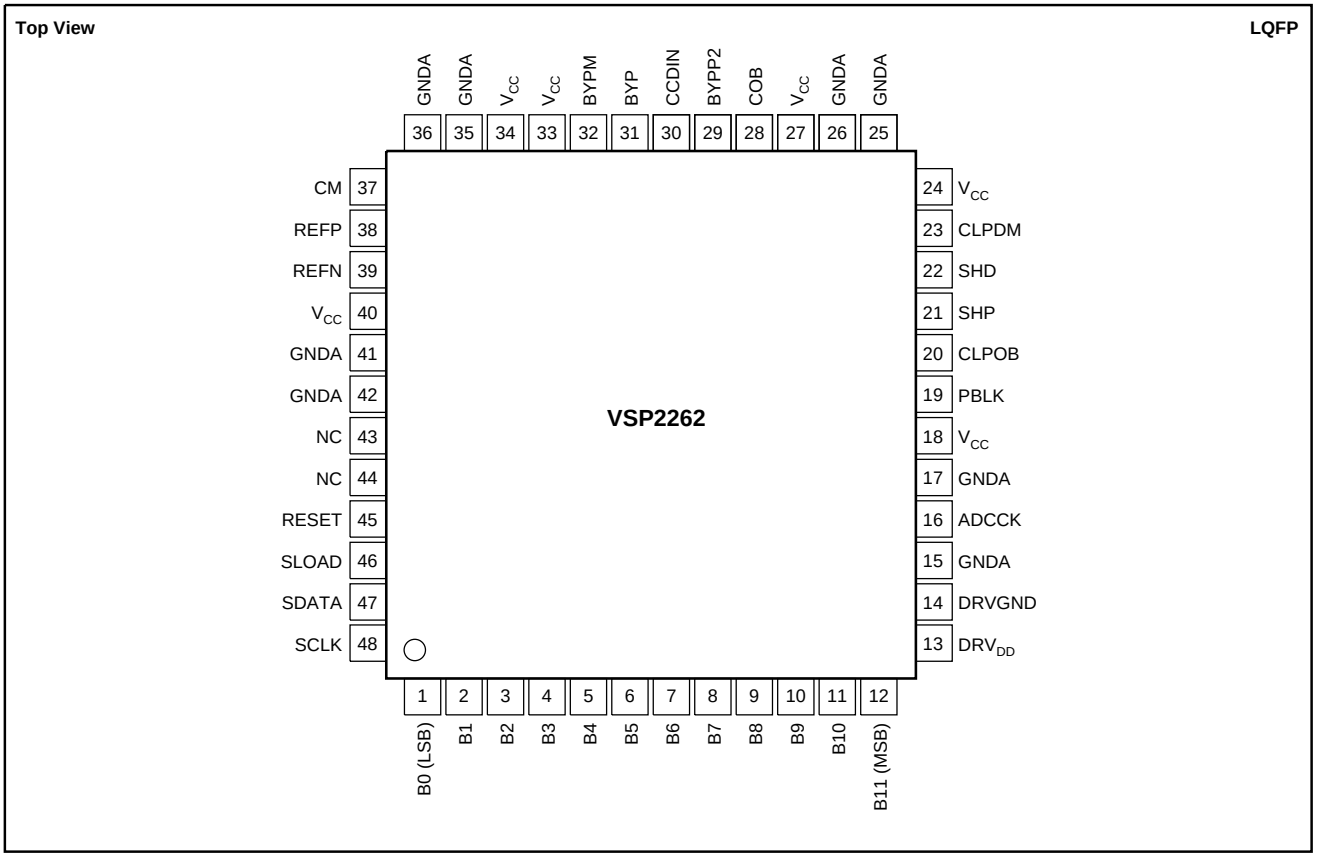
PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER[1]	TRANSPORT MEDIA
VSP2262Y	LQFP-48	340	0 to +85°C	VSP2262Y	VSP2262Y	250-Piece Tray
"	"	"	"	"	VSP2262Y/2K	Tape and Reel

NOTE: (1) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /2K indicates 2000 devices per reel). Ordering 2000 pieces of “VSP2262Y/2K” will get a single 2000 piece Tape and Reel.

DEMO BOARD ORDERING INFORMATION

PRODUCT	ORDERING NUMBER
VSP2262Y	DEM-VSP2262Y

PIN CONFIGURATION

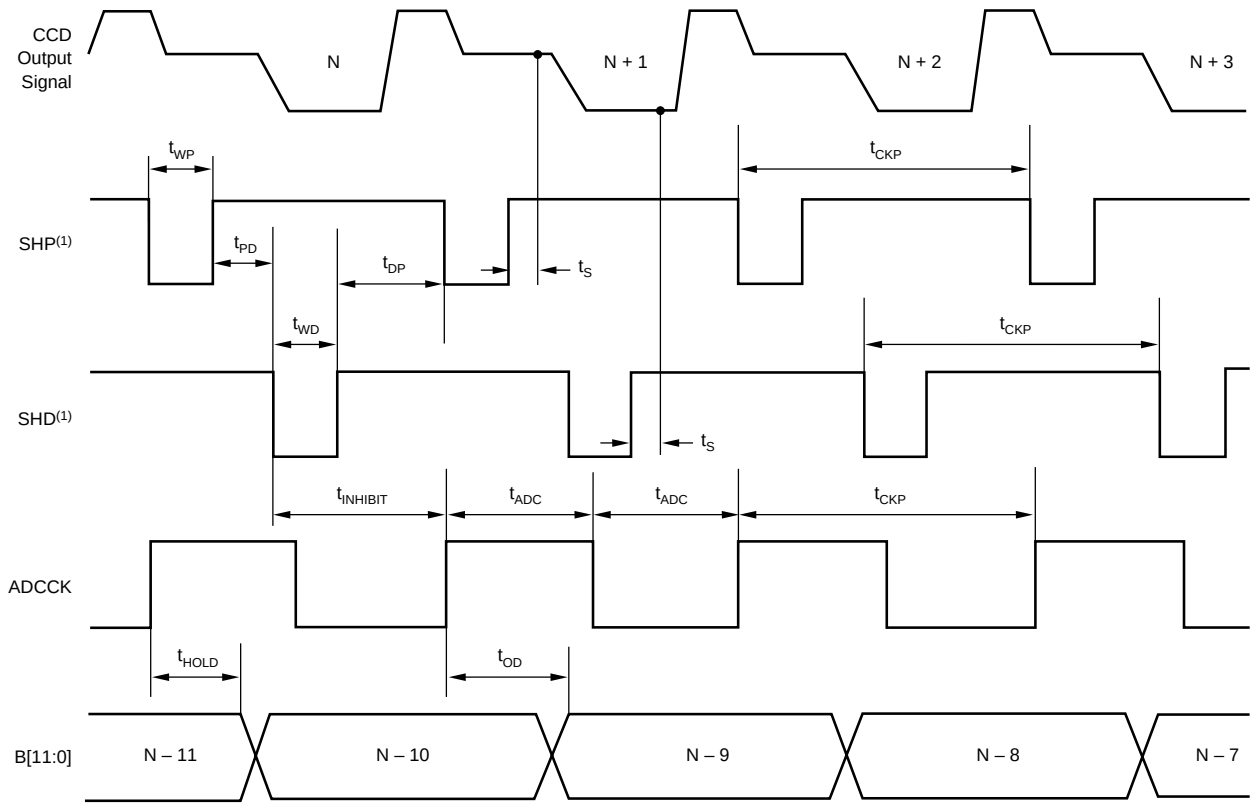


PIN DESCRIPTIONS

PIN	NAME	TYPE[1]	DESCRIPTION	PIN	NAME	TYPE[1]	DESCRIPTION
1	B0 (LSB)	DO	Bit 0 (LSB), A/D Converter Output	24	V_{CC}	P	Analog Power Supply
2	B1	DO	Bit 1, A/D Converter Output	25	GNDA	P	Analog Ground
3	B2	DO	Bit 2, A/D Converter Output	26	GNDA	P	Analog Ground
4	B3	DO	Bit 3, A/D Converter Output	27	V_{CC}	P	Analog Power Supply
5	B4	DO	Bit 4, A/D Converter Output	28	COB	AO	Optical Black Clamp Loop Reference[2]
6	B5	DO	Bit 5, A/D Converter Output	29	BYPP2	AO	Internal Reference P[3]
7	B6	DO	Bit 6, A/D Converter Output	30	CCDIN	AI	CCD Signal Input
8	B7	DO	Bit 7, A/D Converter Output	31	BYP	AO	Internal Reference C[4]
9	B8	DO	Bit 8, A/D Converter Output	32	BYPM	AO	Internal Reference N[3]
10	B9	DO	Bit 9, A/D Converter Output	33	V_{CC}	P	Analog Power Supply
11	B10	DO	Bit 10, A/D Converter Output	34	V_{CC}	P	Analog Power Supply
12	B11 (MSB)	DO	Bit 11 (MSB), A/D Converter Output	35	GNDA	P	Analog Ground
13	DRV_{DD}	P	Power Supply, Exclusively for Digital Output	36	GNDA	P	Analog Ground
14	DRVGND	P	Digital Ground, Exclusively for Digital Output	37	CM	AO	A/D Converter Common-Mode Voltage[4]
15	GNDA	P	Analog Ground	38	REFP	AO	A/D Converter Positive Reference[4]
16	ADCCK	DI	Clock for Digital Output Buffer	39	REFN	AO	A/D Converter Negative Reference[4]
17	GNDA	P	Analog Ground	40	V_{CC}	P	Analog Power Supply
18	V_{CC}	P	Analog Power Supply	41	GNDA	P	Analog Ground
19	PBLK	DI	Preblanking:	42	GNDA	P	Analog Ground
			HIGH = Normal Operation Mode	43	NC	–	Should be Left OPEN
			LOW = Preblanking Mode: Digital Output “All Zero”	44	NC	–	Should be Left OPEN
20	CLPOB	DI	Optical Black Clamp Pulse (Default = Active LOW)[5]	45	RESET	DI	Asynchronous System Reset (Active LOW)
21	SHP	DI	CDS Reference Level Sampling Pulse (Default = Active LOW)[5]	46	SLOAD	DI	Serial Data Latch Signal (Triggered at the Rising Edge)
22	SHD	DI	CDS Data Level Sampling Pulse (Default = Active LOW)[5]	47	SDATA	DI	Serial Data Input
23	CLPDM	DI	Dummy Pixel Clamp Pulse (Default = Active LOW)[5]	48	SCLK	DI	Clock for Serial Data Shift (Triggered at the Rising Edge)

NOTES: (1) Type designators: P = Power Supply and Ground; DI = Digital Input; DO = Digital Output; AI = Analog Input; AO = Analog Output. (2) Should be connected to ground with a bypass capacitor. We recommend the value of 0.1µF to 0.22 µF, however, it depends on the application environment. Refer to the “Optical Black Level Clamp Loop” section for more detail. (3) Should be connected to ground with a bypass capacitor. We recommend the value of 400pF to 9000pF, however, it depends on the application environment. Refer to the “Voltage Reference” section for more detail. (4) Should be connected to ground with a bypass capacitor (0.1µF). Refer to the “Voltage Reference” section for more detail. (5) Refer to “Serial Interface” section for more detail.

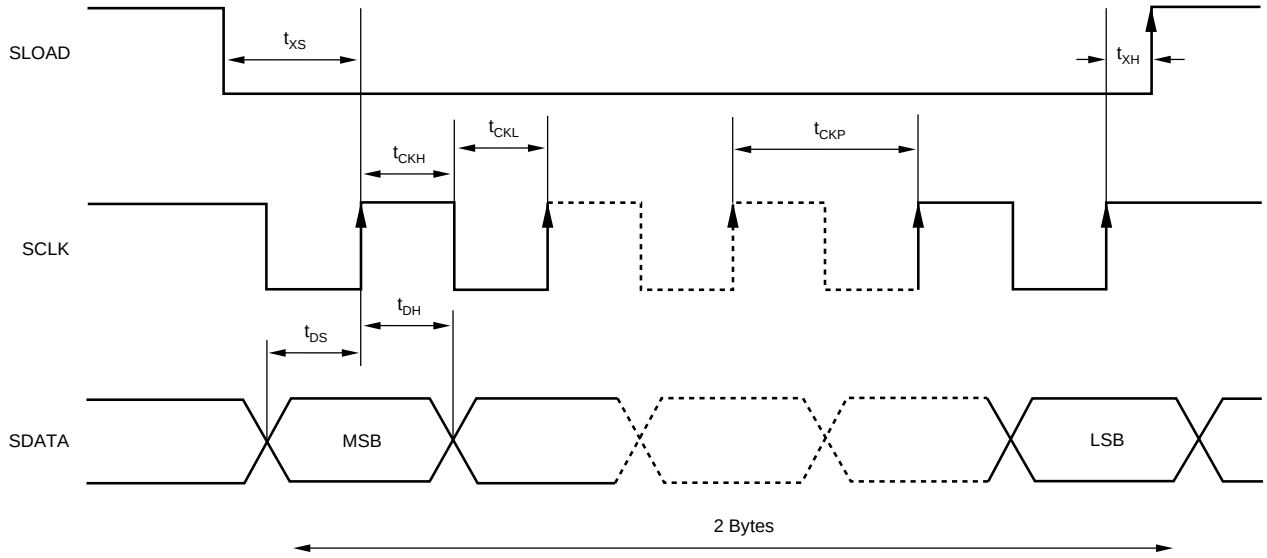
CDS TIMING SPECIFICATIONS



SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS
t_{CKP}	Clock Period	48			ns
t_{ADC}	ADCCK HIGH/LOW Pulse Width	20			ns
t_{WP}	SHP Pulse Width	14			ns
t_{WD}	SHD Pulse Width	11			ns
t_{PD}	SHP Trailing Edge to SHD Leading Edge(1)	8			ns
t_{DP}	SHD Trailing Edge to SHP Leading Edge(1)	12			ns
t_S	Sampling Delay		5		ns
$t_{INHIBIT}$	Inhibited Clock Period	20			ns
t_{HOLD}	Output Hold Time	7			ns
t_{OD}	Output Delay			38	ns
DL	Data Latency, Normal Operation Mode		9 (fixed)		Clock Cycles

NOTE: (1) The description and timing diagrams in this data sheet are all based on the polarity of Active LOW (default value). The user can select the active polarity (Active LOW or Active HIGH) through the serial interface. Refer to the “Serial Interface” section for more detail.

SERIAL INTERFACE TIMING SPECIFICATIONS



SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS
t_{CKP}	Clock Period	100			ns
t_{CKH}	Clock HIGH Pulse Width	40			ns
t_{CKL}	Clcok LOW Pulse Width	40			ns
t_{DS}	Data Setup Time	30			ns
t_{DH}	Data Hold TIme	30			ns
t_{XS}	SLOAD to SCLK Setup Time	30			ns
t_{XH}	SCLK to SLOAD Hold Time	30			ns

NOTES: (1) Data shift operation should occur at the rising edge of SCLK while SLOAD is LOW. Two bytes of input data are loaded to the parallel latch in the VSP2260 at the rising edge of SLOAD. (2) When the input serial data is longer than two bytes (16 bits), the last two bytes become effective and the former bits are lost.

THEORY OF OPERATION

INTRODUCTION

The VSP2262 is a complete mixed-signal IC that contains all of the key features associated with the processing of the CCD imager output signal in a video camera, a digital still camera, security camera, or similar applications (see the simplified block diagram on page 1 for details). The VSP2262 includes a Correlated Double Sampler (CDS), Programmable Gain Amplifier (PGA), Analog-to-Digital Converter (ADC), input clamp, Optical Black (OB) level clamp loop, serial interface, timing control, reference voltage generator, and general-purpose 8-bit Digital-to-Analog Converters (DAC). We recommend an off-chip emitter follower buffer between the CCD output and the VSP2262 CCDIN input. The PGA gain control, clock polarity setting, and operation mode can be selected through the serial interface. All parameters are reset to the default value when the RESET pin goes LOW asynchronously from the clocks.

CORRELATED DOUBLE SAMPLER (CDS)

The output signal of a CCD imager is sampled twice during one pixel period: once at the reference interval and the other at the data interval. Subtracting these two samples from each other extracts the video information of the pixel as well as removes any noise that is common, or correlated, to both the intervals. Thus, the CDS is very important in reducing the reset noise and low-frequency noises that are present on the CCD output signal. Figure 1 shows the simplified block diagram of the CDS and input clamp.

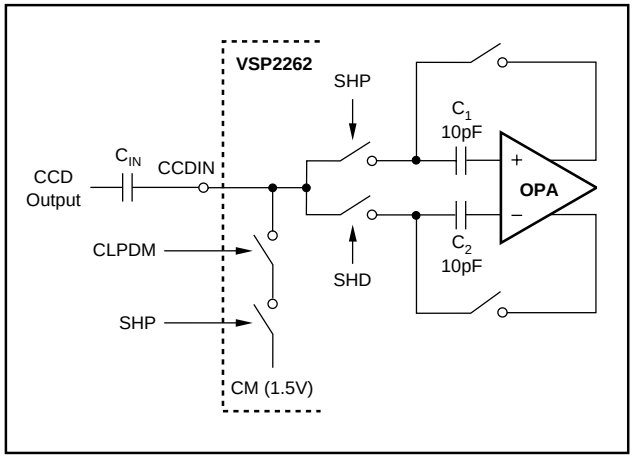


FIGURE 1. Simplified Block Diagram of CDS and Input Clamp.

The CDS is driven through an off-chip coupling capacitor (C_{IN}). AC coupling is strongly recommended because the DC level of the CCD output signal is usually several volts too high for the CDS to work properly.

A 0.1µF capacitor is recommended for C_{IN}, depending on the application environment. Additionally, we recommend an off-chip emitter follower buffer that can drive more than 10pF, because the 10pF capacitor and a few pF of stray capacitance can be seen at the input pin. The analog input signal range at the CCDIN pin is 1Vp-p, and the appropriate common-mode voltage for the CDS is around 0.5V to 1.5V.

The reference level is sampled during SHP active period, and the voltage level is held on sampling capacitor C_1 at the trailing edge of SHP. The data level is sampled during SHD active period, and the voltage level is held on the sampling capacitor C_2 at the trailing edge of SHD. The switched-capacitor amplifier then performs the subtraction of these two levels.

The user can select the active polarity of SHP/SHD (Active HIGH or Active LOW) through the serial interface (refer to the "Serial Interface" section for more detail). The default value of SHP/SHD is "Active LOW". However, immediately after power ON, this value is Unknown. For this reason, the appropriate value must be set by using the serial interface, or reset to the default value by strobing the RESET pin. The descriptions and the timing diagrams in this data sheet are all based on the polarity of Active LOW (default value).

INPUT CLAMP OR DUMMY PIXEL CLAMP

The buffered CCD output is capacitively coupled to the VSP2262. The purpose of the input clamp is to restore the DC component of the input signal that was lost with the AC coupling and establish the desired DC bias point for the CDS. A simplified block diagram of the input clamp is shown in Figure 1. The input level is clamped to the internal reference voltage, CM (1.5V), during the dummy pixel interval. More specifically, when both CLPDM and SHP are active, the dummy clamp function becomes active. If the dummy pixels and/or the CLPDM pulse are not available in your system, the CLPOB pulse can be used in place of CLPDM, as long as the clamping takes place during black pixels. In this case, both the CPLDM pin (active at same timing as CLPOB) and SHP become active during the optical black pixel interval, and then the dummy clamp function becomes active.

The active polarity of CLPDM and SHP (Active HIGH or Active LOW) can be selected through the serial interface (refer to the "Serial Interface" section for more detail). The default value of CLPDM and SHP is "Active LOW". However, immediately after power ON, this value is Unknown. For this reason, the appropriate value must be set by using the serial interface, or reset to the default value by strobing the RESET pin. The descriptions and the timing diagrams in this data sheet are all based on the polarity of Active LOW (default value).

HIGH PERFORMANCE ANALOG-TO-DIGITAL CONVERTER (ADC)

The ADC utilizes a fully differential and pipelined architecture. This ADC is well suited for low-voltage operations, low power consumption requirements, and high-speed applications. It guarantees 12-bit resolution with no missing codes. The VSP2262 includes a reference voltage generator for the ADC. REFP (Positive Reference, pin 38), REFN

(Negative Reference, pin 39), and CM (Common-Mode Voltage, pin 37) should be bypassed to ground with a 0.1µF ceramic capacitor and should not be used elsewhere in the system, as they affect the stability of these reference levels, which causes ADC performance degradation. Note that these are analog output pins and, therefore, do not apply external voltage.

PROGRAMMABLE GAIN AMPLIFIER (PGA)

Figure 2 shows the characteristics of the PGA gain. The PGA provides a gain range of –6dB to +42dB, which is linear in dB. The gain is controlled by a digital code with 10-bit resolution, and can be set through the serial interface (refer to the "Serial Interface" section for more detail). The default value of the gain control code is 128 (PGA Gain = 0dB). However, immediately after power ON, this value is Unknown. For this reason, the appropriate value must be set by using the serial interface, or reset to the default value by strobing the RESET pin.

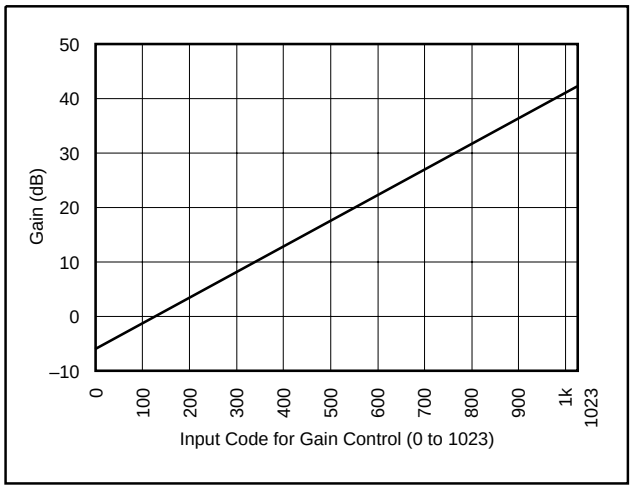


FIGURE 2. The Characteristics of PGA Gain.

OPTICAL BLACK (OB) LEVEL CLAMP LOOP

To extract the video information correctly, the CCD signal must be referenced to a well-established OB level. The VSP2262 has an auto-calibration loop to establish the OB level using the optical black pixels output from the CCD imager. The input signal level of the OB pixels is identified as the real "OB level", and the loop should be closed while CLPOB is active.

During the effective pixel interval, the reference level of the CCD output signal is clamped to the OB level by the OB level clamp loop. To determine the loop time constant, an off-chip capacitor is required, and should be connected to COB (pin 28). Time constant T is given in the following equation:

$$T = C/(16384 \bullet I_{MIN})$$

Where C is the capacitor value connected to COB, I_{MIN} is the minimum current (0.15µA) of the control Digital-to-Analog Converter (DAC) in the OB level clamp loop, and 0.15µA is equivalent to 1LSB of the DAC output current. When C is 0.1µF, time constant T is 40.7µs.

Additionally, the slew rate SR is given the following equation:

$$SR = I_{MAX}/C$$

Where C is the capacitor value connected to COB, I_{MAX} is the maximum current (153µA) of the control DAC in the OB level clamp loop, and 153µA is equivalent to 1023LSB of the DAC output current.

Generally, OB level clamping at high speed causes "Clamp Noise" (or "White Streak Noise"), however, the noise will decrease by increasing C. On the other hand, an increased C requires a much longer time to restore from Stand-by mode, or right after power ON. Therefore, we consider 0.1µF to 0.22µF a reasonable value for C. However, it depends on the application environment; we recommend making careful adjustments using trial-and-error.

The "OB clamp level" (the pedestal level) is programmable through the serial interface (refer to the "Serial Interface" section for more detail). Table I shows the relationship between input code and the OB clamp level.

INPUT CODE	OB CLAMP LEVEL, LSBs OF 12 BITS
0000	2LSB
0001	18LSB
0010	34LSB
0011	50LSB
0100	66LSB
0101	82LSB
0110	98LSB
0111	114LSB
1000 (Default)	**130LSB**
1001	146LSB
1010	162LSB
1011	178LSB
1100	194LSB
1101	210LSB
1110	226LSB
1111	242LSB

TABLE I. Programmable OB Clamp Level.

The active polarity of CLPOB (Active HIGH or Active LOW) can be selected through the serial interface (refer to the "Serial Interface" section for more detail). The default value of CLPOB is "Active LOW". However, immediately after power ON, this value is Unknown. For this reason, the appropriate value must be set by using the serial interface, or reset to the default value by strobing the RESET pin. The descriptions and the timing diagrams in this data sheet are all based on the polarity of Active LOW (default value).

PREBLANKING AND DATA LATENCY

The VSP2262 has an input blanking, or preblanking, function. When PBLK goes LOW, all digital outputs will go to ZERO at the 11th rising edge of ADCCK. In this mode, the digital output data comes out on the rising edge of ADCCK with a delay of 11 clock cycles (data latency is 11). This is

different from the preblanking mode in which the digital output data comes out on the rising edge of ADCCK with a delay of nine clock cycles (data latency is nine).

If the input voltage is higher than the supply rail by 0.3V or lower than the ground rail by 0.3V, the protection diodes will be turned on to prevent the input voltage from going any further. Such a high swing signal may cause device damage to the VSP2262 and should be avoided.

STAND-BY MODE

For the purpose of saving power, the VSP2262 can be set to Stand-by mode (or Power-Down mode) through the serial interface when the VSP2262 is not in use. Refer to the "Serial Interface" section for more detail. In this mode, all the function blocks are disabled and the digital outputs will go to all ZEROs, causing the current consumption to drop to 1mA. Since all the bypass capacitors will discharge during this mode, a substantial time (usually of the order of 200ms to 300ms) is required to power up from Stand-by mode.

VOLTAGE REFERENCE

All the reference voltages and bias currents needed in the VSP2262 are generated by its internal bandgap circuitry. The CDS and the ADC use mainly three reference voltages: REFP (Positive Reference, pin 38), REFN (Negative Reference, pin 39) and CM (Common-Mode Voltage, pin 37). REFP, REFN and CM should be heavily decoupled with appropriate capacitors (e.g., 0.1µF ceramic capacitor). Do not use these voltages elsewhere in the system as they affect the stability of the reference level, and cause ADC performance degradation. Note that these are analog output pins and do not apply external voltage.

BYPP2 (pin 29), BYP (pin 31), and BYPM (pin 32) are also reference voltages to be used in the analog circuit. BYP should be connected to ground with a 0.1µF ceramic capacitor. Since the capacitor value for BYPP2 and BYPM affects the step response, we consider 400pF to 9000pF to be a reasonable value. However, as it depends on the application environment, we recommend making careful adjustments using trial-and-error.

BYPP2, BYP and BYPM should all be heavily decoupled with appropriate capacitors, and not used elsewhere in the system. They affect the stability of the reference levels, and cause performance degradation. Note that these are analog output pins and do not apply external voltage.

SERIAL INTERFACE

The serial interface has a 2-byte shift register and various parallel registers to control all the digitally programmable features of the VSP2262. Writing to these registers is controlled by four signals (SLOAD, SCLK, SDATA, and RESET). To enable the shift register, SLOAD must be pulled LOW. SDATA is the serial data input and the SCLK is the shift clock. The data at SDATA is taken into the shift register at the rising edge of SCLK; the data length should be two bytes. After the 2-byte shift operation, the data in the shift register is transferred to the parallel latch at the rising edge of SLOAD. In addition to the parallel latch, there are several registers dedicated to the specific features of the device and are synchronized with ADCCK. It takes five or six clock cycles for the data in the parallel latch to be written to those registers. Therefore, to complete the data updates, it requires five or six clock cycles after parallel latching by the rising edge of SLOAD.

See Table II for the serial interface data format. TEST is the flag for the test mode (Texas Instruments proprietary only), A0 to A2 is the address for the various registers, and D0 to D11 is the data (or operand) field.

	MSB ←															→ LSB
REGISTERS	**TEST**	**A2**	**A1**	**A0**	**D11**	**D10**	**D9**	**D8**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**
Configuration	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	C0
PGA Gain	0	0	0	1	0	0	G9	G8	G7	G6	G5	G4	G3	G2	G1	G0
OB Clamp Level	0	0	1	0	0	0	0	0	0	0	0	0	O3	O2	O1	O0
Clock Polarity	0	0	1	1	0	0	0	0	0	0	0	0	0	P2	P1	P0
Reserved	0	1	0	0	x	x	x	x	x	x	x	x	x	x	x	x
Reserved	0	1	0	1	x	x	x	x	x	x	x	x	x	x	x	x
Reserved	0	1	1	0	x	x	x	x	x	x	x	x	x	x	x	x
Reserved	0	1	1	1	x	x	x	x	x	x	x	x	x	x	x	x
Reserved	1	x	x	x	x	x	x	x	x	x	x	x	x	x	x	x

x = Don't Care.

TABLE II. Serial Interface Data Format.

REGISTER DEFINITIONS

C[0] **Operation Mode, Normal/Stand-By**

Serial Interface and Registers are always active, independently from the operation mode.

C0 = Operation Mode for the entire chip except the serial interface and registers.

(C0 = 0 "Active"; C0 = 1 "Stand-by")

G[9:0] **The Characteristics of PGA Gain** (refer to Figure 2)

O[3:0] **Programmable OB Clamp Level** (refer to Table I)

P[2:0] **Clock Polarity**

P0 = Polarity for CLPDM (P0 = 0 "Active LOW"; P0 = 1 "Active HIGH")

P1 = for CLPOB (P0 = 0 "Active LOW"; P0 = 1 "Active HIGH")

P2 = for SHP/SHD (P0 = 0 "Active LOW"; P0 = 1 "Active HIGH")

Immediately after power ON, these values are Unknown. The appropriate value must be set by using the serial interface, or reset to the default value by strobing the RESET pin.

Default values are:	
C[2:0] = 0	Normal Operation Mode
G[9:0] = 0010000000	PGA Gain = 0dB
O[3:0] = 1000	OB Clamp Level = 32LSB
P[2:0] = 000	CLPDM, CLPOB, SHP/SHD are all "Active LOW" (1)

NOTE: (1) The descriptions and the timing diagrams in this data sheet are all based on the polarity of Active LOW (default value).

TIMINGS

The CDS and the ADC are operated by SHP/SHD and their derivative timing clocks generated by the on-chip timing generator. The digital output data is synchronized with ADCCK. See the VSP2262 "CDS Timing Specifications" for the timing relationship among the CCD signal, SHP/SHD, ADCCK and the output data. CLPOB is used to activate the black level clamp loop during the OB pixel interval, and CLPDM is used to activate the input clamping during the dummy pixel interval. If the CLPDM pulse is not available in your system, the CLPOB pulse can be used in place of CLPDM as long as the clamping takes place during black pixels (refer to the "Input Clamp and Dummy Pixel Clamp" section for more detail). The clock polarities of SHP/SHD, CLPOB and CLPDM can be independently set through the serial interface (refer to the "Serial Interface" section for more detail). The descriptions and the timing diagrams in this data sheet are all based on the polarity of Active LOW (default value). In order to keep a stable and accurate OB clamp level, we recommend CLPOB should not be activated during PBLK active period. Refer to the "Preblanking and Data Latency" section for more detail. In Stand-by mode, ADCCK, SHP, SHD, CLPOB and CLPDM are internally masked and pulled HIGH.

POWER SUPPLY, GROUNDING AND DEVICE DECOUPLING RECOMMENDATIONS

The VSP2262 incorporates analog circuitry and a very high-precision, high-speed ADC that are vulnerable to any extraneous noise from the rails or elsewhere. For this reason, it should be treated as an analog component and all supply pins except for DRV_{DD} should be powered by the only analog supply of the system. This will ensure the most consistent results, since digital power lines often carry high levels of wideband noise that would otherwise be coupled into the device and degrade the achievable performance. Proper grounding, short lead length, and the use of ground planes are also very important for high-frequency designs. Multi-layer PC boards are recommended for the best performance, since they offer distinct advantages like minimizing ground impedance, separation of signal layers by ground layers, etc. It is highly recommended that analog and digital ground pins of the VSP2262 be joined together at the IC and be connected only to the analog ground of the system. The driver stage of the digital outputs (B[11:0]) is supplied through a dedicated supply pin (DRV_{DD}) and it should be separated from the other supply pins completely, or at least with a ferrite bead.

It is also recommended to keep the capacitive loading on the output data lines as low as possible (typically less than 15pF). Larger capacitive loads demand higher charging current surges that can feed back into the analog portion of the VSP2262 and affect the performance. If possible, external buffers or latches should be used, providing the added benefit of isolating the VSP2262 from any digital noise activities on the data lines. In addition, resistors in series with each data line may help minimize the surge current. Values in the range of 100Ω to 200Ω will limit the instantaneous current the output stage has to provide for recharging the parasitic capacitances as the output levels change from LOW to HIGH, or HIGH to LOW. Due to high operation speed, the converter also generates high-frequency current transients and noises that are fed back into the supply and reference lines. This requires the supply and reference pins to be sufficiently bypassed. In most cases, 0.1µF ceramic chip capacitors are adequate to decouple the reference pins. Supply pins should be decoupled to the ground plane with a parallel combination of tantalum (1µF to 22µF) and ceramic (0.1µF) capacitors. The effectiveness of the decoupling largely depends on the proximity to the individual pin. DRV_{DD} should be decoupled to the proximity of DRVGND. Special attention must be paid to the bypassing of COB, BYPP2 and BYPM, since these capacitor values determine important analog performances of the device.

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